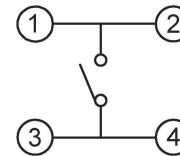
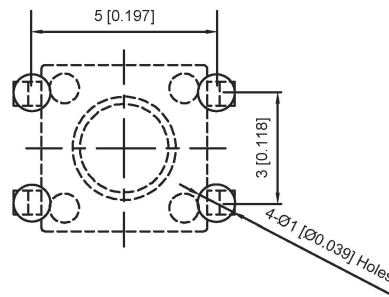
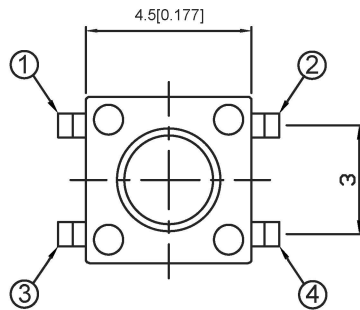


CIRCUIT DIAGRAM



Code-x	H
A	3.8
B	4.3
C	4.5
D	5.0
E	5.5
F	6.0
G	6.5
H	7.0
I	7.5
J	8.0
K	8.5
L	9.0

P.C.B MOUNTING PATTERN DIMENSION
The following soldering patterns are recommended for reflow soldering



SPECIFICATION

Contact Rating: 50mA, 12V DC
 Contact Resistance: 100mΩ max
 Insulation Resistance: 100mΩ min. 500V DC
 Dielectric Strength: 250V AC/1minute
 Travel: 0.25mm
 Operating Temp: -30□ ~ +85□
 Storage Temp: -30□ ~ +80□

PAPT NO	TC-1109-X-X
Operating Force	A: 100gf B: 160gf C: 260gf
Height	Code-X

ITEM	PAPT NAMF	TER.NO	QTY	MATERIAL	FINISHING	REMARK
⑤	Terminal	—	4	Brass (0.30t)	Plating silvering	—
④	Contact	—	1	F.ag/Sus	Natural	—
③	Base	—	1	Pa46	—	—
②	Cover	—	1	Spcc	Plating Nickel	—
①	Keystake	—	1	Pa46	—	—

广东星坤科技股份有限公司

生	ΔX	日期
效	ΔX	日期
ΔX	ΔX	日期
MARK	MARK	日期

DSND	DATE	SCALE: N/A	MODEL TYPE: TACT SWITCH
DWN	DATE	VIEW:	PART NO.:
CHKD	DATE	UNIT: mm/in	DWG NO.:
APPD	DATE	SIZE: A4	TC-1109-X-X
XKB INDUSTRIAL PRECISION CO., LIMITED			WEIGHT 1.0g
			SHEET 1/1
			REVISION A0

文件工程章

REVISIONS
UNSPECIFIED TOLERANCES
www.helloxb.com www.helloxb.com